

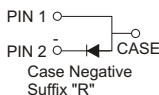


FEATURES

- * Low forward voltage drop
- * High current capability
- * High reliability
- * High surge current capability
- * Good for switching mode application

MECHANICAL DATA

- * Case: Molded plastic
- * Epoxy: UL 94V-0 rate flame retardant
- * Lead: Axial leads, solderable per MIL-STD-202, method 208 guaranteed
- * Polarity: Color band denotes cathode end
- * Mounting position: Any



VOLTAGE RANGE
1200 Volts
CURRENT
8.0 Ampere

GK xxx
MUR8120



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25°C ambient temperature unless otherwise specified.
Single phase half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

TYPE NUMBER	MUR8120	UNITS
Maximum Recurrent Peak Reverse Voltage	1200	V
Maximum RMS Voltage	840	V
Maximum DC Blocking Voltage	1200	V
Maximum Average Forward Rectified Current	8.0	A
Peak Forward Surge Current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	150	A
Maximum Instantaneous Forward Voltage at 8.0A Type at 8.0A Type at 5.0A	2.6 2.1 1.95	V
Maximum DC Reverse Current Ta=25°C	5	μA
at Rated DC Blocking Voltage Ta=100°C	100	μA
Maximum Reverse Recovery Time (Note 1)	60	nS
Typical Junction Capacitance (Note 2)	65	pF
Typical Thermal Resistance RθJ-C (Note 3)	1.8	°C/W
Typical Thermal Resistance RθJ-A (Note 4)	50	°C/W
Reverse recovery charge Q _{rr}	120	nC
Operating and Storage Temperature Range T _J , T _{STG}	-65 — +175	°C

NOTES:

1. Reverse Recovery Time test condition: IF=0.5A, IR=1.0A, IRR=0.25A
2. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
3. Between junction and case

RATING AND CHARACTERISTIC CURVES

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

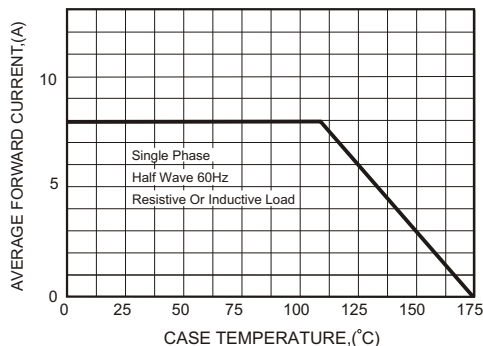
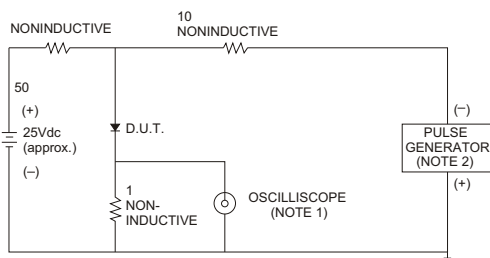


FIG.3- TEST CIRCUIT DIAGRAM AND REVERSE RECOVERY TIME CHARACTERISTICS



NOTES: 1. Rise Time= 7ns max., Input Impedance= 1 megohm, 22pF.

2. Rise Time= 10ns max., Source Impedance= 50 ohms.

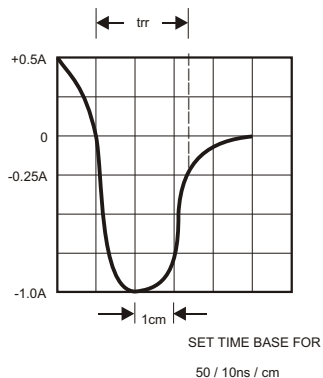


FIG.5 - TYPICAL REVERSE CHARACTERISTICS

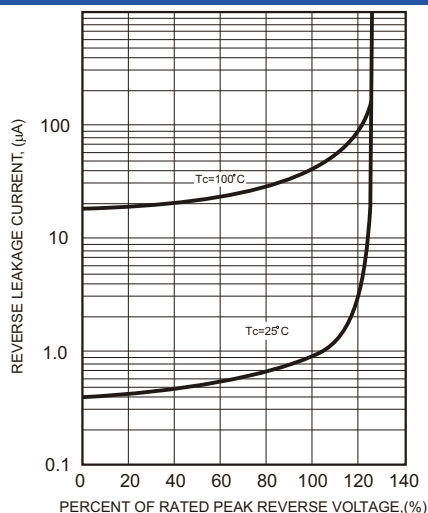


FIG.2-TYPICAL FORWARD CHARACTERISTICS

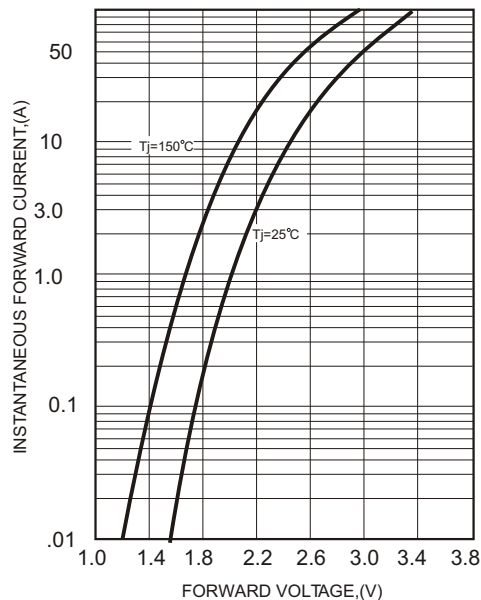


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

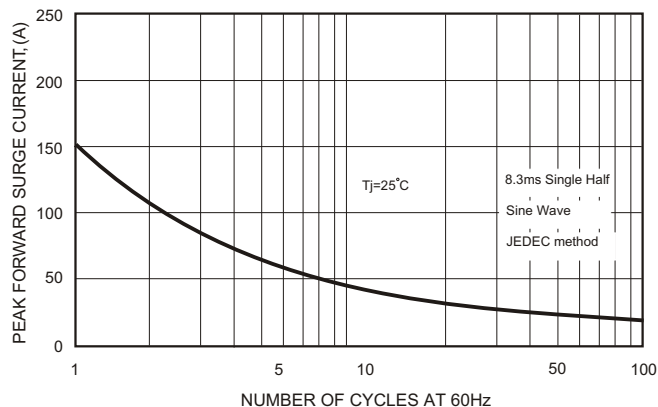
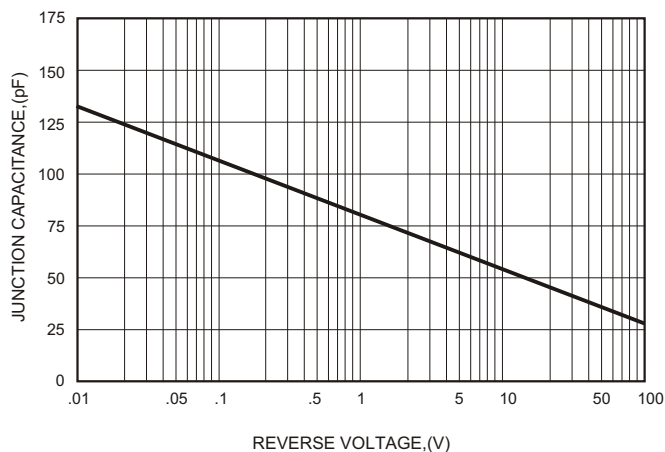
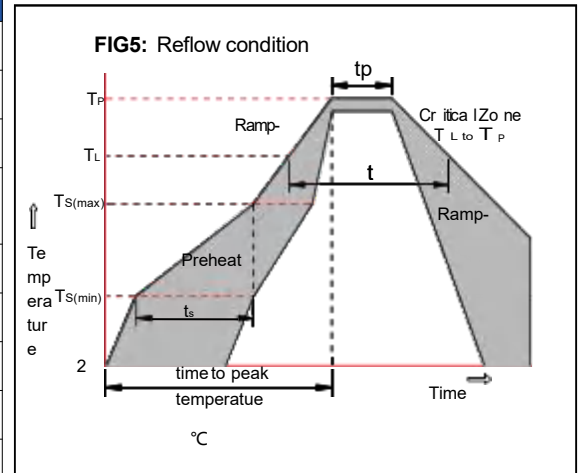


FIG.6-TYPICAL JUNCTION CAPACITANCE



Soldering parameters

Reflow Condition		Pb-Free assembly (see as below)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max($T_{s(max)}$)	+200°C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3°C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217°C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_P)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp (T_P)		8 min. Max
Do not exceed		+260°C



Package Dimensions & Suggested Pad Layout

